

**REPLY UNDER 37 CFR §1.116**  
**EXPEDITED PROCEDURE**  
**TECHNOLOGY CENTER 2800**

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

In re application of:  
Hsien-Wei Chen, et al. § Attorney Docket No.  
§ 2003-1410 / 24061.193  
§  
Serial No.: 10/801,475 § Customer No. 42717  
§  
Filed: March 16, 2004 § Group Art Unit: 2822  
§  
For: SYSTEM FOR HEAT § Examiner: Monica Lewis  
DISSIPATION IN §  
SEMICONDUCTOR DEVICES § Confirmation No.: 1783

**Mail Stop AF**  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Sir:

I hereby certify that this correspondence (including any listed enclosures) is being electronically filed in the United States Patent and Trademark Office via the EFS-Web system on October 9, 2007.

  
Linda Ingram

**RESPONSE UNDER 37 C.F.R. §1.116**

This Response is submitted in reply to the Office Action mailed on September 14, 2007.  
(Please see the pages that follow).